



1109252

52 PIN PLCC PACKAGE MOTOROLA MC68HC11E9 TO 56 PIN SDIP PACKAGE

FEATURES:

- Allows placing an PLCC package part on a board laid out for a shrink dip.

SPECIFICATIONS:

- Board material is .062 [1.58] thick FR-4 with 1 oz. Copper traces, both sides.
- Pads are HASL.
- Pins are Brass Alloy 360 1/2 hard per UNS C36000 ASTM-B16-00.
- Pin plating is Tin/Lead 93/7 per ASTM B 545 over 100µ [2.54µm] Nickel per SAE-AMS-QQ-N-290.
- Operating Temperature=221°F [105°C].
- Female socket is an AMP or equivalent standard single beam PLCC socket.

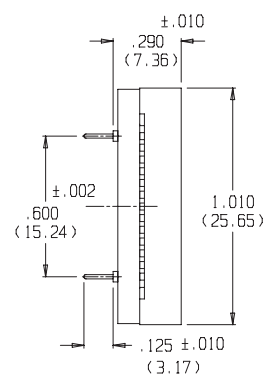
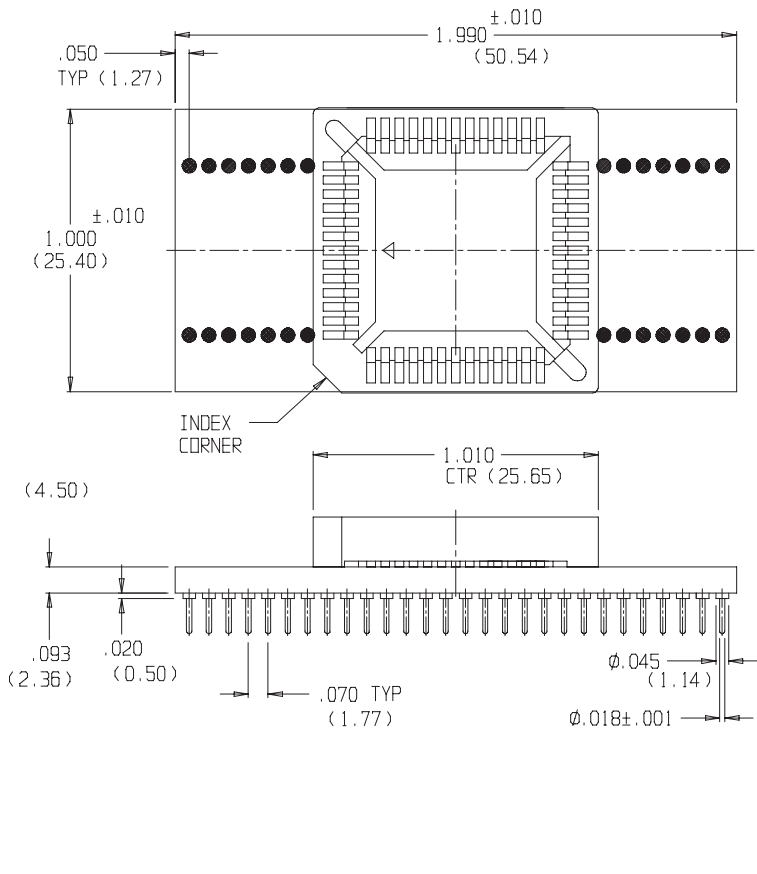
MOUNTING CONSIDERATIONS:

- Solder process just like any other surface mount device.

PLCC	DSIP	PLCC	SDIP
1	1	--	29
2	2	27	30
3	3	28	31
4	4	29	32
5	5	30	33
6	6	31	34
7	7	32	35
8	8	33	36
9	9	34	37
10	10	35	38
11	11	36	39
12	12	37	40
13	13	38	41
14	14	39	42
15	15	40	46
16	16	41	44
17	17	42	45
18	18	43	46
19	19	44	47
20	20	45	48
--	21	46	49
21	22	47	50
22	23	48	51
23	24	49	52
24	25	50	53
25	26	51	54
26	27	52	55
--	28	--	56

ALL DIMENSIONS: INCHES [MILLIMETERS]

All tolerances ± .005 [.13] unless otherwise specified



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REV. F